

**IEEE**

19th INTERNATIONAL SYMPOSIUM ON THE PHYSICAL AND FAILURE ANALYSIS OF INTEGRATED CIRCUITS

IPFA 2012

2 – 6 July 2012
MARINA BAY SANDS
SINGAPORE

2nd CALL FOR PAPERS

The 19th International Symposium on the Physical and Failure Analysis of Integrated Circuits (IPFA 2012) is organized by the IEEE Reliability/CPMT/ED Singapore Chapter. The Symposium is technically co-sponsored by the IEEE Electron Device Society and IEEE Reliability Society. Also, IPFA will be celebrating its 25th year in 2012.

IPFA 2012 will be devoted to the fundamental understanding of the physical mechanisms of semiconductor device failures and issues related to semiconductor device reliability and yield, especially those related to advanced process technologies. The Technical Programme Committee is inviting papers related, but not limited to, the following areas:

- Sample Preparation, Metrology and Material Characterization
- Advanced Failure Analysis Techniques
- Die-Level / Package-Level Failure Analysis Case Study & Failure Mechanisms
- Product Reliability Evaluation and Approaches
- Novel Device Reliability and Failure Mechanisms
- Novel Gate Stack/Dielectrics and FEOL Reliability and Failure Mechanisms
- Advanced Interconnects and BEOL Reliability and Failure Mechanisms

SUBMISSION GUIDELINES

Prospective authors are requested to submit one cover page and a two-page summary (includes text and figures) of their previously unpublished and original research work.

The cover page should contain the following information:

1. Title of the work.
2. Name, affiliation, and address of each author.
3. Telephone number, fax number and e-mail address of the corresponding author
4. An abstract not exceeding 50 words.
5. The category/categories (FEOL, BEOL, Failure Analysis techniques, etc.) that you would like your submission to be considered under.
6. Presentation mode: Oral or poster presentation or no preference.

The summary section of the submission should not contain any reference to the authors or their affiliation, and should present the content of the submission according to the following sub-headings:

1. Brief introduction to the background and motivation/objectives of the work.
2. Experimental results, analysis and discussion.
3. Summary of the findings, highlighting their impact, novelty and importance.
4. Supporting figures, tables, and references.

All submissions must be in English. Please submit your abstract through the IPFA Website <http://www.ieee.org/ipfa> by **18 January 2012**. Please limit your submission file size to 2 MB. Hardcopy submissions will not be accepted. For further details please contact the Technical Program Chair.

Authors of papers that have been accepted for presentation will be notified by 14 March 2012. Upon notification of acceptance, authors will be asked to submit a final manuscript (to be submitted by 9 May 2012) such that it can be published in the Symposium Proceedings and presented at the symposium.

IMPORTANT DATES:

18 January 2012
14 March 2012
9 May 2012

Submission of Summary and Abstract
Notification of Paper Acceptance
Submission of Final Manuscript

LATE BREAKING NEWS MANUSCRIPTS

The conference also accepts important findings as late papers. Full-papers, no longer than 4 pages, should be submitted by 18 April 2012 for consideration. The acceptance of such papers is limited to break-through findings and is subject to space availability and scheduling considerations. Accepted late papers will be included in the conference proceedings and in the technical presentations at the conference.

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